

December 1992

DESCRIPTION

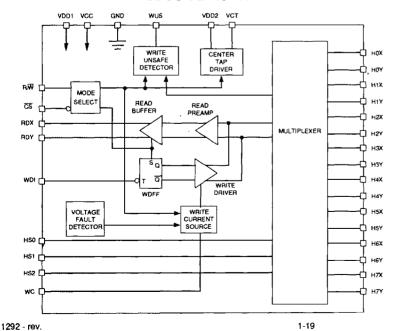
The SSI 32R516 is a bipolar monolithic integrated circuit designed for use with a center-tapped ferrite or MIG recording heads. The SSI 32R516 offers the performance upgrades of the SSI 32R511 along with improved head port characteristics and increased read gain. It provides a low noise read path, write current control, and data protection circuitry for as many as 8 channels. The SSI 32R516 requires +5V and +12V power supplies and is available in a variety of packages.

The SSI 32R516R performs the same function as the SSI 32R516 with the addition of internal 650Ω damping resistors. The SSI 32R516M and SSI 32R516RM are functionally equivalent to the SSI 32R516 and SSI 32R516R however, they have the mirror image pin arrangement to simplify layout when using multiple devices.

FEATURES

- High performance
 - Read mode gain = 120 V/V
 Input noise = 1.3 nV/√Hz maximum
 Input capacitance = 18 pF
 Write current range = 10 mA to 60 mA
- Enhanced system write to read recovery time
- · Power supply fault protection
- Pin compatible with the SSI 32R501 & SSI 32R511
- Designed for center-tapped ferrite or MIG heads
- Programmable write current source
- · Easily multiplexed for larger systems
- Includes write unsafe detection
- TTL compatible control signals
- +5V, +12V power supplies
- Mirror image pin arrangements

BLOCK DIAGRAM



PIN DIAGRAM

нох [Ť		32	þ	GND
ноч [2		31	þ	N/C
H1X [3		30	þ	cs
ніч [4		29	þ	₽√₩
н2х [5		28	þ	wc
H2Y [6		27	þ	ADY
нзх [7		26	þ	RDX
нју [8	32R516-8/ 32R516R-8	25	þ	HS0
H4X [9	8 Channeis	24	þ	HS1
H4Y [10		23	þ	н\$2
н5х [11		22	þ	vcc
н5Ү [12		21	þ	WDI
нех [13		20	þ	wus
H6Y [14		19	þ	VDD
н7х [15		18	þ	VDD
н7Ү [16		17	þ	VCT
	_				

32-Lead SOW

CAUTION: Use handling procedures necessary for a static sensitive component.

CIRCUIT OPERATION

The SSI 32R516 gives the user the ability to address up to 8 center-tapped ferrite heads and provide write drive or read amplification. Head selection and mode control is accomplished using the HSn, CS and R/W inputs as shown in tables 1 & 2. Internal pullups are provided for the CS & R/W inputs to force the device into a nonwriting condition if either control line is opened accidentally.

TABLE 1: Mode Select

cs	R/W	MODE
0	0	Write
0	1	Read
1	X	ldle

TABLE 2: Head Select

HS2	HS1	HS0	HEAD
0	0	0	0
0	0	1	1
0	1	0	2
0	1	1	3
1	0	0	4
1	0	1	5
1	1	0	6
1	1	1	7

0 = Low level 1 = High level

WRITE MODE

Taking both CS and R/W low selects write mode which configures the SSI 32R516 as a current switch and activates the Write Unsafe (WUS) detector circuitry. Write current is toggled between the X and Y side of the selected head on each high to low transition of the Write Data Input (WDI). Note that a preceding read mode selection initializes the Write Data Flip-Flop, WDFF, to pass write current through the "X" side of the head. The zero-peak write current magnitude is programmed by an external resistor Rwc from pin WC to GND and is given by:

Iw = K/Rwc, where K = Write Current Constant

The Write Unsafe detection circuitry monitors voltage transitions at the selected head connections and flags any of the following conditions as a high level on the Write Unsafe open collector output:

- Head open
- · Head center tap open
- · WDI frequency too low · Device in read mode
- Device not selected
- No write current

Two negative transitions on WDI, after the fault is corrected, will clear the WUS flag.

To further assure data security a voltage fault detection circuit prevents application of write current during power loss or power sequencing.

To enhance write to read recovery time the change in RDX, RDY common mode voltage is minimized by biasing these outputs to a level within the read mode range when in write mode.

Power dissipation in write mode may be reduced by placing a resistor (RCT) between VDD1 & VDD2. The optimum resistor value is $82\Omega \times 60/\text{lw}$ (lw in mA). At low write currents (<15 mA) read mode dissipation is higher than write mode and RCT, though recommended, may not be considered necessary. In this case VDD2 is connected directly to VDD1.

READ MODE

Taking CS low and R/W high selects read mode which configures the SSI 32R516 as a low noise differential amplifier for the selected head. The RDX and RDY outputs are driven by emitter followers and are in phase with the "X" and "Y" head ports. These outputs should be AC coupled to the load. The internal write current source is gated off in read mode eliminating the need for any external gating.

Read mode selection also initializes the Write Data Flip-Flop (WDFF) to pass write current through the "X" side of the head at a subsequent write mode selection.

IDLE MODE

Taking CS high selects the idle mode which switches the RDX, RDY outputs into a high impedance state and deactivates the internal write current source. This facilitates multi-device installations by allowing the read outputs to be wire OR'ed and the write current programming resistor to be common to all devices.

PIN DESCRIPTIONS

NAME	I/O	DESCRIPTION
HS0-HS2	ı	Head Select
CS	Į.	Chip Select: a low level enables device
R/W	1	Read/Write: a high level selects read mode
wus	0,	Write Unsafe: a high level indicates an unsafe writing condition
WDI	L	Write Data In: negative transition toggles direction of head current
H0X-H7X H0Y-H7Y	I/O	X,Y head connections
RDX, RDY	0*	X, Y Read Data: differential read signal out
wc	•	Write Current: used to set the magnitude of the write current
VCT	-	Voltage Center Tap: voltage source for head center tap
vcc	-	+5V
VDD1	-	+12V
VDD2	-	Positive power supply for the center tap voltage source
GND	-	Ground

^{*}When more than one R/W device is used, these signals can be wire OR'ed.

ELECTRICAL SPECIFICATIONS

ABSOLUTE MAXIMUM RATINGS (All voltages referenced to GND. Currents into device are positive.)

PARAMETER		VALUE	UNITS
DC Supply Voltage	VDD1	-0.3 to +14	VDC
DC Supply Voltage	VDD2	-0.3 to +14	VDC
DC Supply Voltage	VCC	-0.3 to +6	VDC
Digital Input Voltage Range	VIN	-0.3 to VCC + 0.3	VDC
Head Port Voltage Range	VH	-0.3 to VDD1 + 0.3	VDC
WUS Pin Voltage Range	Vwus	-0.3 to +14	VDC
Write Current Zero Peak	IW	90	mA
RDX, RDy Output Current	lo	-10	mA
VCT Output Current	lvct	-90	mA
WUS Output Current	Iwus	+12	mA
Storage Temperature Range	Tstg	-65 to 150	°C
Lead Temperature PDIP, Flat P (10 sec Soldering)	ack ack	260	°C
Package Temperature PLCC, S (20 sec Reflow)	60	215	°C

RECOMMENDED OPERATION CONDITIONS

PARAMETER		CONDITIONS	MIN	МОМ	MAX	UNITS
DC Supply Voltage	VDD1		10.8	12.0	13.2	VDC
DC Supply Voltage	vcc		4.5	5.0	5.5	VDC
Head Inductance	Lh		5		10	μН
Damping Resistor	RD	32R516 only	500		2000	Ω
RCT Resistor	RCT*	lw = 60 mA		82		Ω
Write Current	IW		10		60	mA
Junction Temperature Range	Tj		+25		+135	∘C

^{*}For lw = 60 mA. At other lw levels refer to Applications Information that follows this specification.

DC CHARACTERISTICS

(Unless otherwise specified, recommended operating conditions apply.)

POWER SUPPLY

PARAMETER	CONDITIONS	MIN	NOM	MAX	UNITS
VCC Supply Current	Read/Idle Mode			30	mA
	Write Mode			30	mA
VDD Supply Current	Idle Mode			20	mA
(sum of VDD1 and VDD2)	Read Mode			40	mA
	Write Mode			20 + W	mA
Power Dissipation (Tj = +125°C)	Idle Mode			400	mW
	Read Mode			620	mW
	Write Mode, IW = 45 mA, RCT = 0Ω			800	mW
	Write Mode, IW = 45 mA, RCT = 110Ω			610	mW
	Write Mode, IW = 60 mA RCT = 82Ω			680	mW

DC CHARACTERISTICS (continued)

DIGITAL I/O

PARA	METER	CONDITIONS	MIN	МОМ	MAX	UNITS
VIL	Input Low Voltage				0.8	VDC
VIH	Input High Voltage		2.0		VCC + 0.3	VDC
IIL	Input Low Current	VIL = 0.8V	-0.4		,	mA
IIH	Input High Current	VIH = 2.0V			100	μА
VOL	WUS Output Low Voltage	IOL = 8 mA			0.5	VDC
IOH	WUS Output High Current	VOH = 5.0V			100	μA

WRITE MODE

Center Tap Voltage VCT	Write Mode		6.9		VDC
Head Current (per side)	Write Mode, 0 ≤ VCC ≤ 3.7V, 0 ≤ VDD1 ≤ 8.7V	-200		200	μА
Write Current Range		10		60	mA
Write Current Constant "K"	IW = 10 - 60 mA	2.375		2.80	V
lwc to Head Current Gain			0.99		mA/mA
Unselected Head Leakage Current	**			85	μΑ
RDX, RDY Output Offset Voltage	Write/Idle Mode	-20		+20	mV
RDX, RDY Common Mode Output Voltage	Write/Idle Mode		5.5		VDC
RDX, RDY Leakage	RDX, RDY = 6V Write/Idle Mode	-100		100	μА

READ MODE

Center Tap Voltage	Read Mode		4.2		VDC
Head Current (per side)	Read or Idle Mode 0 ≤ VCC ≤ 5.5V 0 ≤ VDD1 ≤ 13.2V	-200		200	μА
Input Bias Current (per side)				45	μА
Input Offset Voltage	Read Mode	-4		+4	m∨
Common Mode Output Voltage	Read Mode	4.5	5.5	6.5	VDC

DYNAMIC CHARACTERISTICS AND TIMING

(Unless otherwise specified, recommended operating conditions apply and IW = 35 mA, Lh = 5 μ H, Rd = 750 Ω (32R516) only, f(WDI) = 5 MHz, CL(RDX, RDY) \leq 35 pF.)

WRITE MODE

PARAMETER	CONDITIONS	MIN	МОМ	MAX	UNITS
Differential Head Voltage Swing		7.0			V(pk)
Unselected Head Transient Current				2	mA(pk)
Differential Output Capacitance				15	pF
Differential Output Resistance	32R516	10K			Ω
	32R516R	430	650	870	Ω
WDI Transition Frequency	WUS = low	125			kHz

READ MODE

Differential Voltage Gain	Vin = 1 mVpp @ 300 kHz, RL(RDX), RL(RDY) = 1 KΩ	100	120	140	V/V
Dynamic Range	AC Input Voltage, Vi, Where Gain Falls by 10%. V + f = 300 KHz	-3			mVpp
Bandwidth (-3dB)	Zs < 5Ω, Vin = 1 mVpp	30		,	MHz
Input Noise Voltage	BW = 15 MHz, Lh = 0, Rh = 0		1.0	1.3	nV/√Hz
Differential Input Capacitance	f = 5 MHz		14	18	pF
Differential Input Resistance	32R516, f = 5 MHz	2K			Ω
Differential Input Resistance	32R516R, f = 5 MHz	350		800	Ω
Common Mode Rejection Ratio	Vcm = VCT + 100 mVpp @ 5 MHz	50			dB
Power Supply Rejection Ratio	100 mVpp @ 5 MHz on VDD1, VDD2 or VCC	45			dB
Channel Separation	Unselected Channels: Vin=100 mVpp @ 5 MHz; Selected Channel: Vin = 0 mVpp	45			dB
Single Ended Output Resistance	f = 5 MHz			30	Ω
Output Current	AC Coupled Load, RDX to RDY	±2.1			mA

DYNAMIC CHARACTERISTICS AND TIMING (continued)

SWITCHING CHARACTERISTICS

PARAMETER	CONDITIONS	MIN	МОМ	MAX	UNITS
R/₩ To Write	Delay to 90% of Write Current	-	.15	.7	μѕ
R/W to Read	Delay to 90% of 100 mV, 10 MHz Read Signal Envelope or to 90% decay of Write Current		.25	.7	μs
CS to Select	Delay to 90% of Write Current or to 90% of 100 mV, 10 MHz Read Signal Envelope		.2	1.0	μѕ
CS to Unselect	Delay to 90% Decay of Write Current	· -	.1	1.0	μs
HS0 - HS2 to any head	Delay to 90% of 100 mV, 10 MHz Read Signal Envelope		.25	1.0	μѕ
WUS, Safe to Unsafe - TD1	lw = 35 mA	1.6		8.0	μs
WUS, Unsafe to Safe - TD2	lw = 35 mA			1.0	μs
Head Current (Lh = 0 μ H, Rh = 0 Ω)					
Prop. Delay - TD3	From 50% Points			25	ns
Asymmetry	WDI has 50% Duty Cycle and 1ns Rise/Fall Time			1	ns
Rise/Fall Time	10% - 90% Points			20	ns

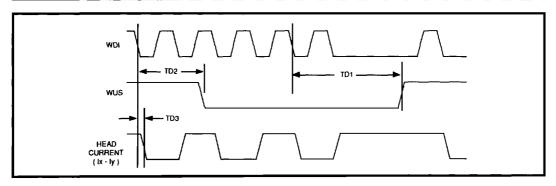
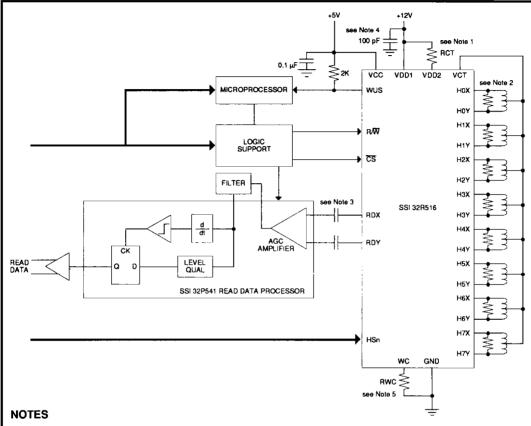


FIGURE 1: Write Mode Timing Diagram

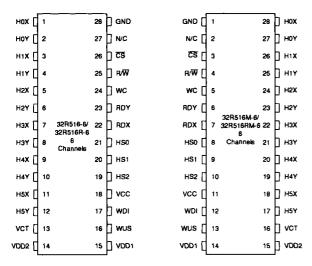


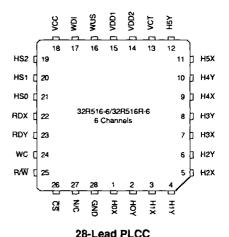
- An external resistor, RCT, given by; RCT = 82 (60/lw) where lw is the zero-peak write current in mA, can be used to limit internal power dissipation. Otherwise connect VDD2 to VDD1.
- 2. Damping resistors not required on 32R516R versions.
- 3. Limit DC current from RDX and RDY to 100 μA and load capacitance to 20 pF. In multi-chip application these outputs can be wire-OR'ed.
- 4. The power bypassing capacitor must be located close to the 32R516 with its ground returned directly to device ground, with as short a path as possible.
- 5. To reduce ringing due to stray capacitance this resistor should be located close to the 32R516. Where this is not desirable a series resistor can be used to buffer a long WC line. In multi-chip applications a single resistor common to all chips may be used.

FIGURE 2: Applications Information

1-26

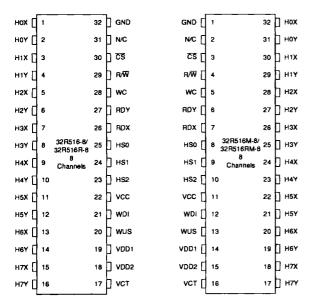
PACKAGE PIN DESIGNATIONS (Top View)





28-Lead SOL

28-Lead SOL Mirror Image



GND [1 N/C ी टड N/C [R₩ нох П h HOY [WC н₁х ∏ RDY 32R516-4/ RDX HIY [] 32R516R-4 H2X [] HS0 h H2Y [17 HS1 нзх П 16 h vcc нзү D WOI VCT] wus

24-Lead SOL

32-Lead SOW

32-Lead SOW Mirror Image

PACKAGE PIN DESIGNATIONS (Continued)

нох [1		34	þ	GND
ноч [2		33	þ	N/C
н1х [3		32	þ	N/C
ніх [4		31	þ	cs
н2х [5		30	þ	R∕₩
н2ү [6		29	þ	wc
нзх [7		28	þ	ROY
нзү [8		27	þ	RDX
н4х [9	32R516-8/	26	þ	HS0
H4Y [10	32R516R-8 8-Channels	25		HS1
н5х [11		24	þ	HS2
н5ү [12		23	þ	vcc
н6х [13		22	þ	WDI
H6Y [14		21	þ	wus
н7х [15		20	þ	N/C
нуу [16		19	þ	VDD1
∨ст [17		18	þ	ADD5
				•	

GND [1 34 | HOX 33 HOY N/C [] 3 32 H1X CS | 4 31 H1Y R/₩ [5 30 HSX 29 H2Y 28 H3X RDY 7 RDX [27 H3Y HSO 9 32R516-8/ 26 H4X HS1 [10 8-Channels 25] H4Y 24 | H5X HS2 [11 vcc [23 H5Y WDI [13 22 H6X 21 H6Y N/C [15 20 H7X 19 H7Y VDD1 [16 18 VCT VDD2 [17

34-Lead SOL

34-Lead SOL Mirror Image

THERMAL CHARACTERISTICS: θja

24-lead	SOL	75°C/W
28-lead	PLCC	65°C/W
	SOL	75°C/W
32-lead	sow	60°C/W
34-lead	SOL	70°C/W
44-lead	PLCC	50°C/W

ORDERING INFORMATION

PART DESCRIPTION	ORDER NO.	PKG. MARK		
SSI 32R516				
4-Channel SOL	32R516-4CL	32R516-4CL		
6-Channel PLCC	32R516-6CH	32R516-6CH		
6-Channel SOL	32R516-6CL	32R516-6CL		
8-Channel SOW	32R516-8CW	32R516-8CW		
8-Channel SOL	32R516-8CL	32R516-8CL		
SSI 32R516R				
4-Channel SOL	32R516R-4CL	32R516R-4CL		
6-Channel PLCC	32R516R-6CH	32R516R-6CH		
6-Channel SOL	32R516R-6CL	32R516R-6CL		
8-Channel SOW	32R516R-8CW	32R516R-8CW		
8-Channel SOL	32R516R-8CL	32R516R-8CL		
SSI 32R516M				
6-Channel SOL	32R516M-6CL	32R516M-6CL		
8-Channel SOW	32R516M-8CW	32R516M-8CW		
8-Channel SOL	32R516M-8CL	32R516M-8CL		
SSI 32R516RM				
6-Channel SOL	32R516RM-6CL	32R516RM-6CL		
8-Channel SOW	32R516RM-8CW	32R516RM-8CW		
8-Channel SOL	32R516RM-8CL	32R516RM-8CL		

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